Docket No.:

	# <u></u>	LAKATION FOR PA	IENI	APPLICATION				
As a below named inven	tor(a) (we)	hereby declare that:						
My (our) residence(s), poname(s).	ost office ad	dress(es) and citizenship	(s) is (ar	re) the same as stated be	low next to r	ny (our)		
I (we) believe I am (we a and joint inventor (if plur sought on the invention of IN SILICON SIN	entitled: ME	THOD OF IDENTIFYIN	lect mai	ter which is claimed and	· /) or an origir for which a p	nal, first patent is		
the specification of which [X] was filed onI PCT Internations	ebruary 2	23,2004 as United Stat	es Appli	ication Number 10/784	,411	or		
and was amende	ed on	oplication Number (if applicable).						
I (we) hereby state that I including the claims, as a	(we) have r amended by	eviewed and understand any amendment referred	the cont I to abo	tents of the above identifive.				
I (we) acknowledge the c Federal Regulations, §1.	56.	ise information which is n	naterial	to patentability as defined	d in Title 37,	Code of		
I (we) hereby claim foreig application(s) for patent op patent or inventor's certif	or inventor's	Centificate listed below a	nd have	alco idontified below		lication for		
		r Foreign Application(s):				 		
(Number)		(Country)		(Day/Month/Year)	Priority Claimed: YES NO			
			 		 			
I (we) hereby claim the bapplication(s) listed below	enefit under w:	Title 35, United States C	ode, §1	19(e) of any United State	s provisiona	l		
(Application Number) (Filing Date)								
I (we) hereby claim the b below and, insofar as the States application in the acknowledge the duty to Regulation, §1.56 which international filing date o	manner prov disclose info became ava	rided by the first paragraph ormation which is materia	of this a oh of Tit	application is not disclose the 35, United States Code	d in the prior e, § 112, I (w	United (e)		
(Application Serial	No.)	(Filing date)		(STATUS = 4 = 4				
		(Filling date)		(STATUS-patented, pending, abandoned)				
			-					
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DECLARATION FOR PATENT APPLICATION

I (we) hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith and to act in accordance with the instructions from Suda Patent Office:								
Lloyd McAulay, Jules E. Goldberg, Eugene LeDonne, Arthur Dresner,		Reg. No. 24,408; Reg. No. 35,930;	J. Harold Nissen, Gerald H. Kiel, Stephen M. Chin, Samir R. Patel,	Reg. No. 17,283; Reg. No. 25,116; Reg. No. 39,938; Reg. No. 44,998				
all of Reed Smith LLP, 599 LEXINGTON AVENUE, NEW YORK, N.Y 10022 U.S.A.								
Address all telephone calls to:		Jules E. Goldberg, Esq.	at Telephone No. (212) 521-5400				
Address all correspondence to:		Jules E. Goldberg, Esq. Reed Smith LLP 599 LEXINGTON AVENUE, NEW YO	YORK, N.Y 10022 U.S.A.					
I (we) hereby declare that all statements made herein of my (our) own knowledge are true, and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.								
Full name of sole or 1st inventor (given name, family name):		Jun FURUKAWA						
Residence:	Tokyo, Japan		Citizenship:	Japanese				
Post Office Address:	c/o Sumitomo Mitsubishi Silicon Corporation, 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan							
Inventor's signature: Jun Jurukama Date: 16.2.2004								
Full name of 2nd inventor (given name, family name):			Kazunari KURITA					
Residence:	Tokyo, Japan		Citizenship:	Japanese				
Post Office Address:	c/o Sumitomo Mitsubishi Silicon Corporation, 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan							
Inventor's signature: Kazuwari Kurifa Date: 10, 2, 2004								
Full name of 3rd inventor (given name, family name):			Kazuhiro HARADA					
Residence:	Tokyo, Japan		Citizenship:	enship: Japanese				
Post Office c/o Sumitomo Mitsubishi Silicon Corporation, 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan								
Inventor's signature: Kajuhiro Harada Date: 16.2.2004								